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**Oohashi et al.**

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(54) **ABSORPTION BOARD FOR AN ELECTRIC CHUCK USED IN SEMICONDUCTOR MANUFACTURE**

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(\*\*) Term: **14 Years**

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(52) **U.S. Cl.** ..... **D13/182**

(58) **Field of Classification Search** ..... D13/182;  
156/345.53; 279/128; 361/234

See application file for complete search history.

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(57) **CLAIM**

We claim the ornamental design for an absorption board for an electric chuck used in semiconductor manufacture, as shown.

**DESCRIPTION**

FIG. 1 is a perspective view of an absorption board for an electric chuck used in semiconductor manufacture.

FIG. 2 is a front elevational view thereof.

FIG. 3 is a rear elevational view thereof.

FIG. 4 is a right side elevational view thereof, the left side elevational view being a mirror image and not shown; and,

FIG. 5 is a top plan view thereof, the bottom plan view being a mirror image and not shown.

**1 Claim, 4 Drawing Sheets**

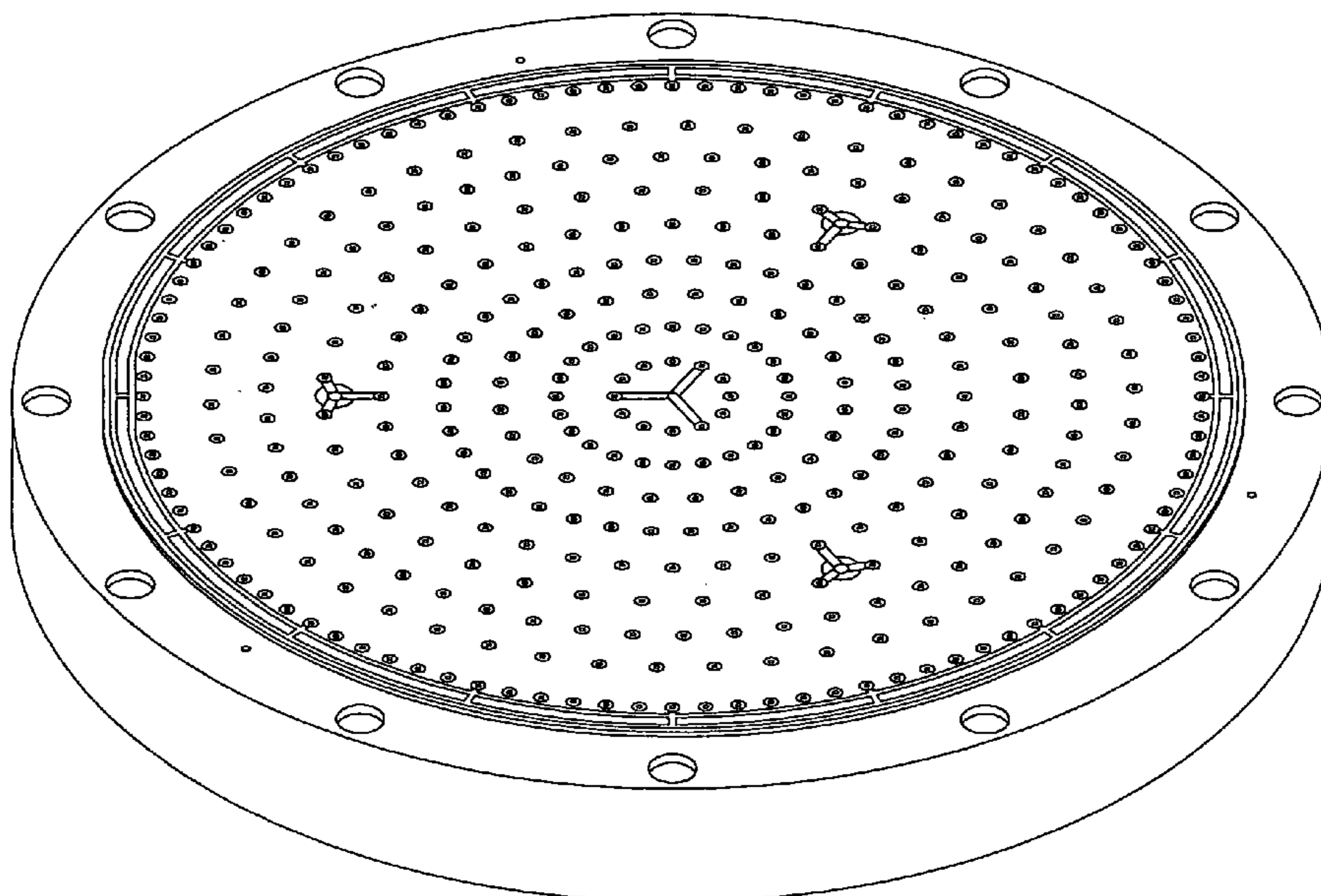


FIG. 1

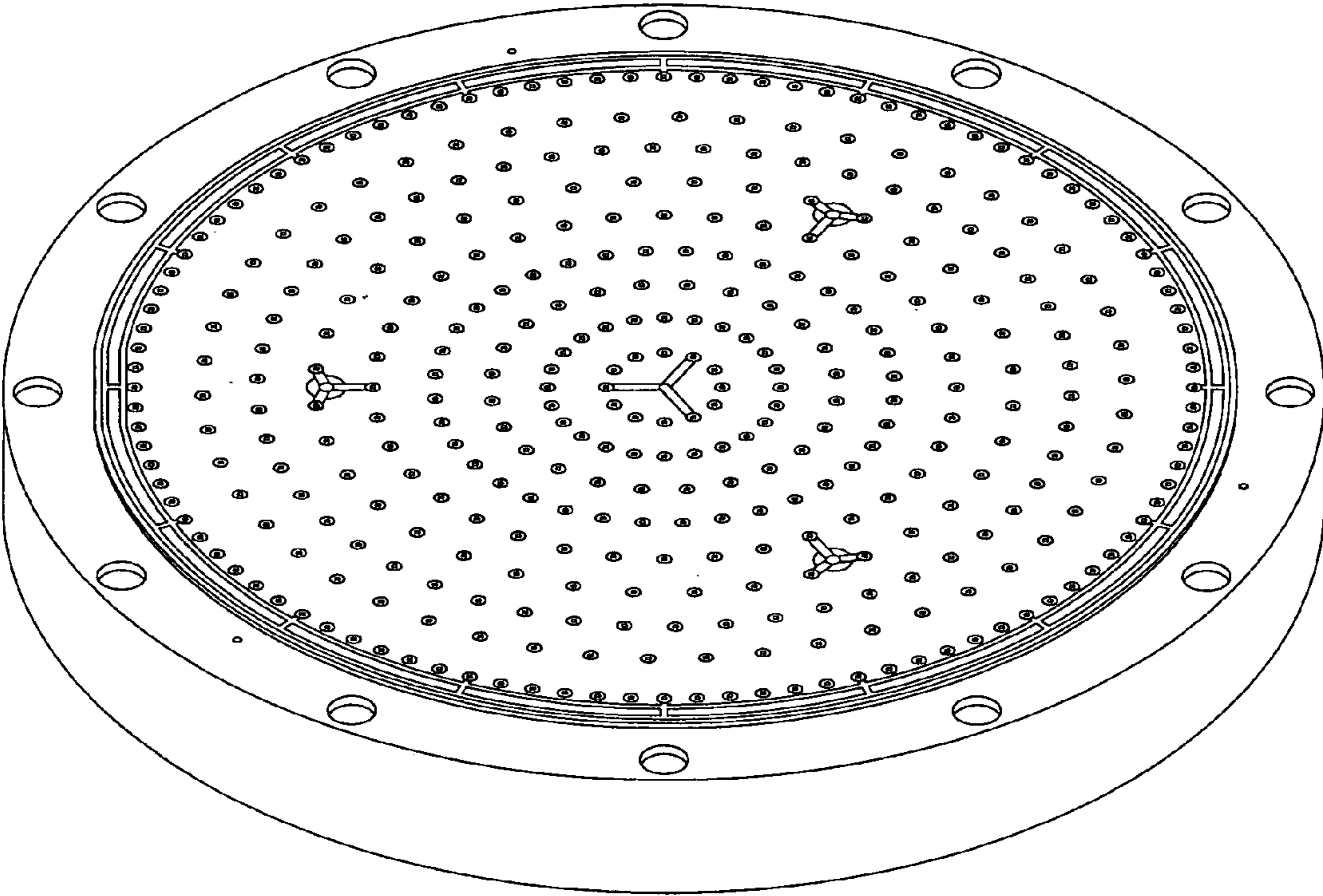


FIG. 2

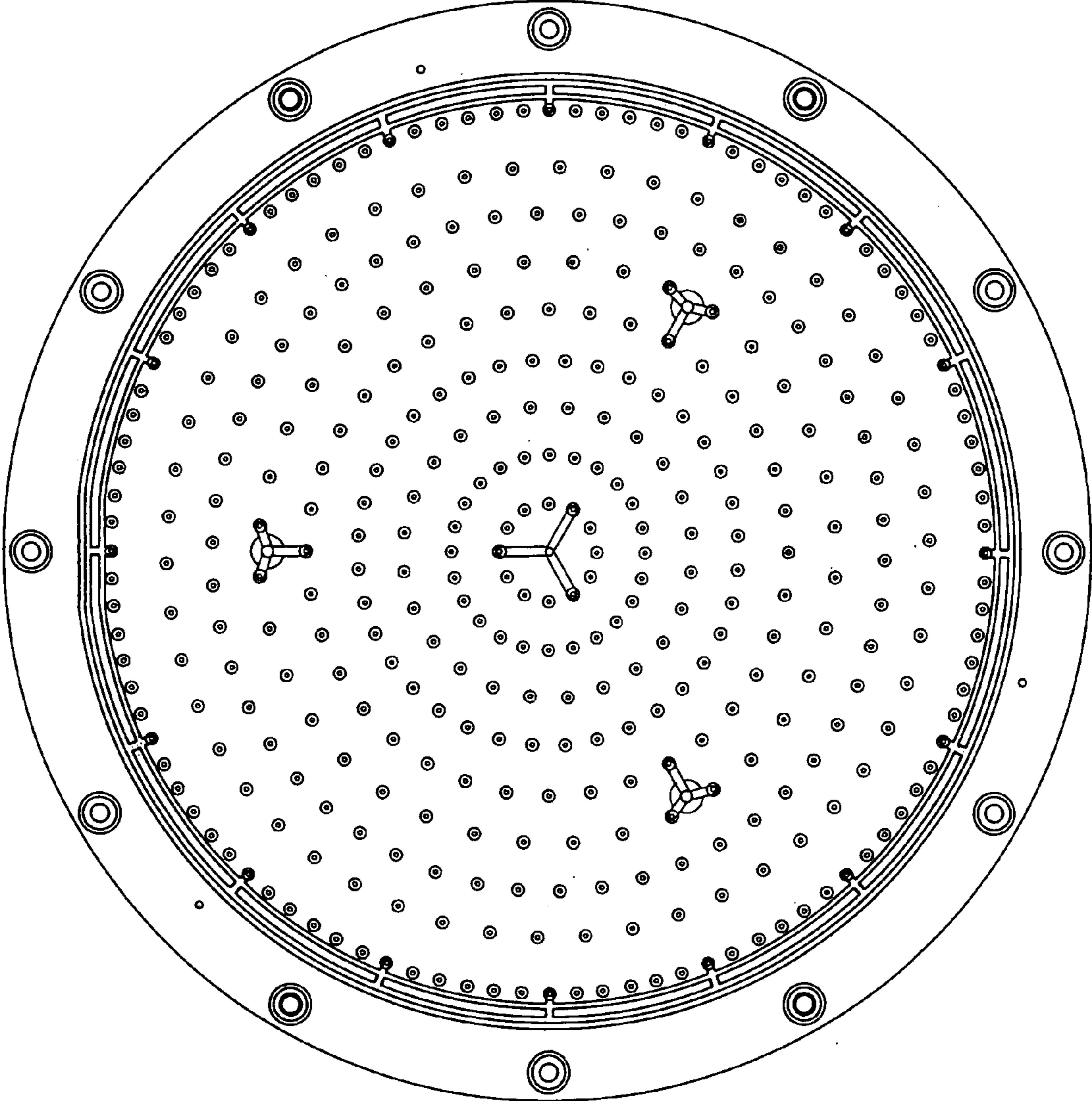


FIG. 3

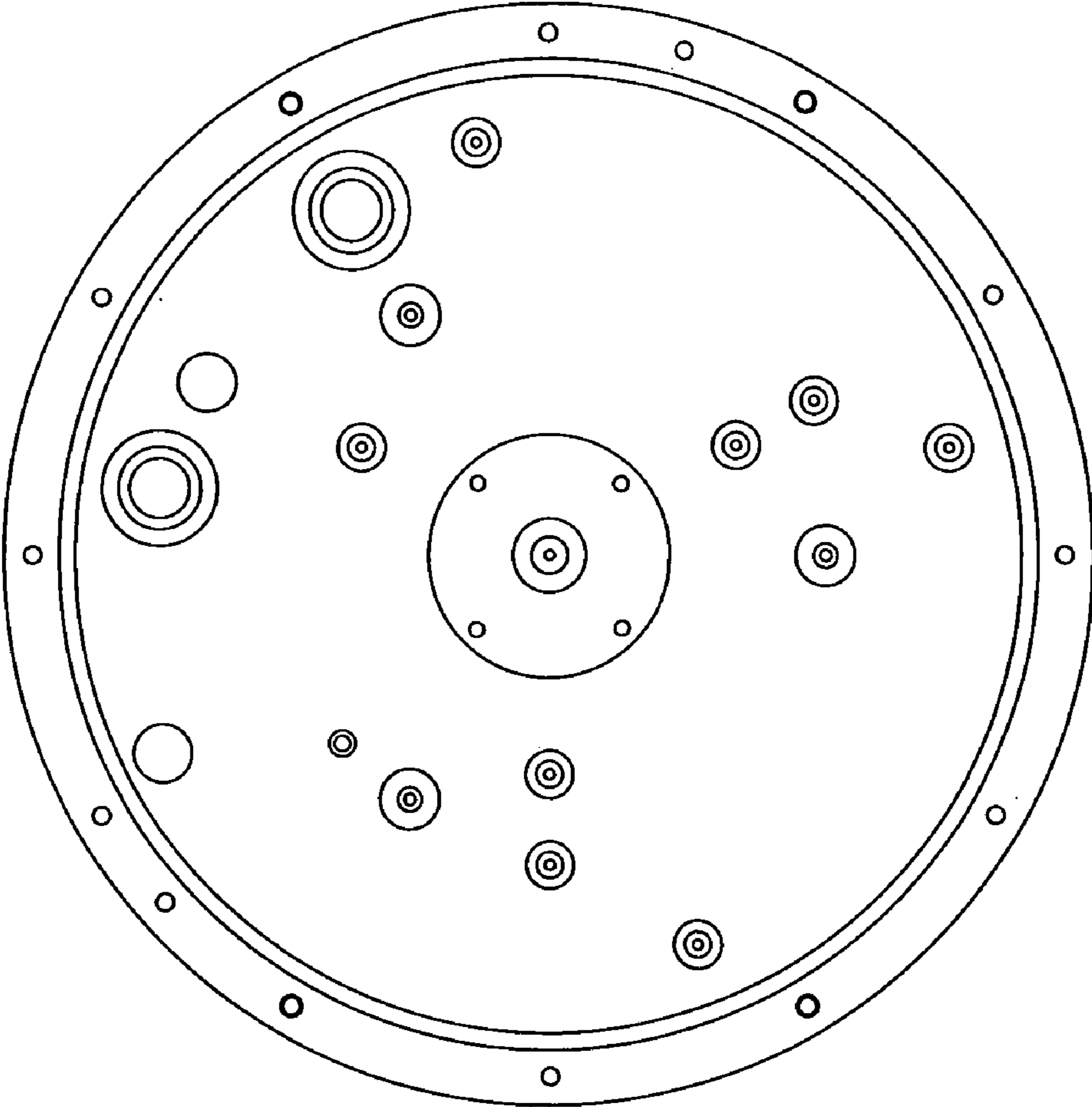


FIG. 4

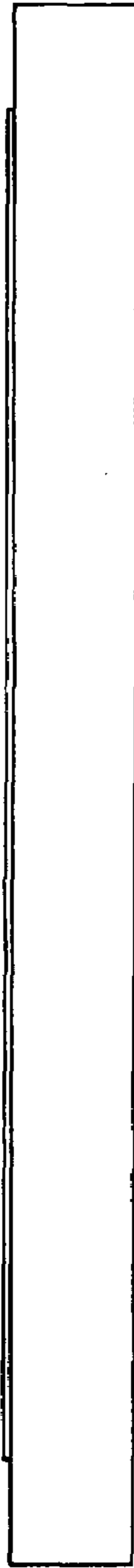


FIG. 5

